AMENDMENTS TO THE SPECIFICATION

Please replace paragraph **[0086]** with the following amended paragraph:

[0086] Next, and with reference to Figure 11, the loader 910 may be re-inserted into the substrate bonding device while supporting the second substrate 120. Upon loading the second substrate 120 into the substrate bonding device, the lift pin 710 may be raised from its original position, through the lower stage 230 and from below the upper surface of the lower stage 230, to push the second substrate 120 away from the loader 910. Accordingly, the lift pin 710 may support the second substrate [[210]] 120 at a predetermined height above the loader 910 (as shown in Figure 12). When the second substrate 120 is supported at the predetermined height, the loader 910 may be removed from the substrate bonding device. Next, the lift pin 710 may be lowered such that the second substrate 120 rests on, and is supported by, the lower stage 240. When the second substrate 120 is supported by the lower stage 240, the second substrate 120 may be secured to the lower stage 240 using suction forces and electrostatic charges. When the first and second substrates 110 and 120 are secured to their respective stages 230 and 240, loading of the substrate bonding device is complete.

Please replace paragraph **[0088]** with the following amended paragraph:

[0088] Referring to Figure 14, as a result of the lowering of the upper chamber unit 210 and of the projection of the moveable shafts [[511]] 512, the end portions of the moveable shafts 512 may be received within, and contact interior surfaces of respective ones of the holes 222a formed in the lower chamber plate 222. In the event that, for example, the upper chamber unit 210 is not substantially level with respect to the lower chamber unit 220, the movable shafts [[511]] 512 may contact the interior surfaces of the holes 222a in succession. As the end portions of the moveable shafts [[511]] 512 are received within the holes 222a, the chamber moving means moves the upper chamber unit 210 downwardly such that a bottom surface of the upper chamber plate 212 contacts a top surface of the third sealing member 250, fitted to a periphery of the lower chamber plate 222.

Please replace paragraph **[0094]** with the following amended paragraph:

[0094] According to the principles of the present invention, the lower stage 240 is fixed to a top surface of the lower base 221. Accordingly, the position of the lower chamber plate 222 with respect to the lower stage 240 may be adjusted. Since the upper stage 230 does not move with respect to the upper chamber plate [[210]] 212, the upper stage 230 moves in substantial unison with the movement of the lower chamber plate 222 via the interlocking means 510. Therefore, to adjust the alignment of the first and second substrates 110 and 120, fixed to their respective stages 230 and 240, the motion of the lower chamber plate 222, generated by the alignment means (e.g., rotation of the cams 531, 532, 533, and 534 at the peripheral surfaces of the lower chamber plate 222), may be translated through the interlocking means 510 to the upper stage 230, fixed to the upper chamber unit 210.

Please replace paragraph **[00125]** with the following amended paragraph:

[00125] According to the principles of the present invention, the protection sheet 860 may substantially cover a surface of the lower stage 240 (or of the upper stage 230), wherein opposite ends of the protection sheet may be wound around the first and second reels 851 and [[862]] 852 and wherein the protection sheet 860 may substantially prevent the accumulation of foreign matters on the surface of the lower stage 240 (or upper stage 230).